Special Issue

New Trends in Image Processing III

Message from the Guest Editors

In the last few years, the methodologies and technologies related to video processing, imaging processing, computer graphics, 3D modelling, and multimedia have seen significant implementation in the field of computer vision. The continuous development of these technologies has led to an introduction of new methodologies and applications in this field. Moreover, recent image-processing machine learning algorithms, especially deep learning, provide an opportunity to efficiently process massive datasets in order to extract information and develop new analysis procedures. The aim of this Special Issue is two-fold: firstly, this Issue shows novel applications of modern devices for data acquisition and visualization (e.g., CCTV videos, 3D scanners, VR glasses, robots), and, secondly, it proposes new methodologies for huge dataset processing using modern pattern recognition and machine learning approaches (e.g., deep learning and hypergraph learning).

Guest Editors

Prof. Dr. Hyeonjoon Moon

Department of Computer Science and Engineering, Sejong University, Seoul 05006, Republic of Korea

Dr. Irfan Mehmood

Faculty of Engineering & Informatics, School of Media, Design and Technology, University of Bradford, Bradford, UK

Deadline for manuscript submissions

closed (20 August 2023)

Applied Sciences

mdpi.com/journal/
applsci

About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32, 20133 Milano, Italy

Author Benefits

Open Access:
free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility:
indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, CAPlus / SciFinder, and other databases.

Journal Rank:
JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)

MDPI